

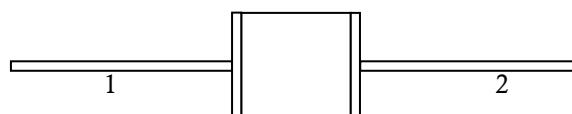
Features



- Size Design $\Phi 5.5 \times 6\text{mm}$
- High Current Handling Capability 3,000A @ 8/20 μ s
- Low Capacitance and Insertion Loss
- Fast Response and Long Service Life
- Reliable to Protect Electrostatic Surge
- Moisture sensitivity level: Level 1

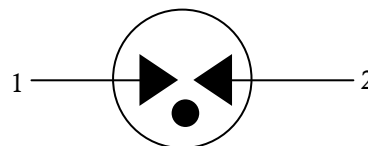
Exterior

Application Information

- AC Power

Package (Top View)

Agency Approvals

Icon	Description
RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003
	Mean lead free
	Compliance with UL1449, Certificated E337906

Schematic Symbol

Electrical Parameter

DC Breakdown Voltage ^{1) 2)}	100V/s	3600(-20%~+30%)	V
Impulse Spark-over Voltage	1.2/50 μ s-8/20 μ s 6KV-3KA	≤ 5500	V
Impulse Spark-over Voltage	At 1kV/ μ s	for 99 % of measured values ≤ 4700	V
	At 1kV/ μ s	Typical values of distribution ≤ 4600	V
Impulse Discharge Current ³⁾	8/20 μ s ± 5 times	3	KA
Arc Voltage	At 1A	~ 15	V
Insulation Resistance	DC=100V	≥ 1	G Ω
Capacitance at 1 MHz	V _{DC} =0.5V	≤ 1	pF
Hi-pot Test	I _D =10mA	≥ 1875	V
Weight		~ 0.75	g
Operating and storage Temperature		-40-90	$^{\circ}\text{C}$
Marking		Bencent Logo, Voltage and date code	

1) At delivery AQL 0.65 level II ISO 2859

2) In ionized mode

3) Terms and current waveforms in accordance with ITU-T Rec. K. 12; IEC 61643-21

Part Numbering System

B5G XXXX

(1) (2)

 (1) Bencent 2-Electrode DIP Gas Discharge Tube with dimension: $\Phi 5.5 \times 6$ (D×L) (mm)

(2) DC Breakdown Voltage, e.g., 3600=3600V

Product Characteristics

Lead Material	Copper
Body Material	Ceramics Iron-nickel electrode
Terminal Finish	100% Matte-Tin Plated

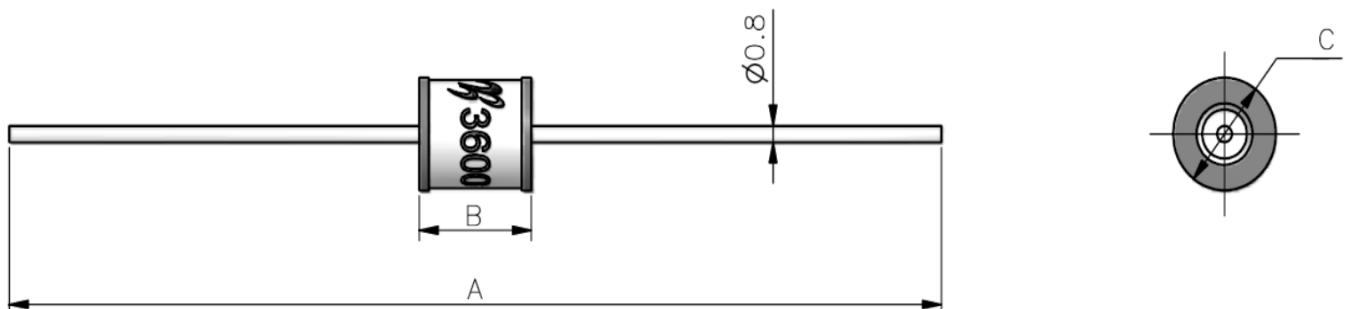
Environmental Reliability Characteristics

Testing items	Technical standards
High Temperature Storage Test	Temperature: 90°C Time: 2H
Low Temperature Storage Test	Temperature: -40°C Time: 2H
Vibration	Frequency: 10-500Hz Amplitude: 0.15mm Time: 45mins
Resistance of soldering heat	Temperature: 260±5°C Time of dip soldering: 10s, 1time

Note: Up-screen program can be specified by customer's request via contacting Bencent service

Solderability Test

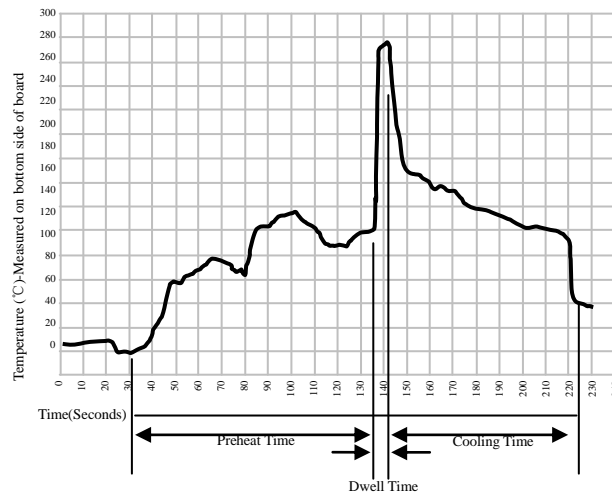
Solderability	Solder Pot Temperature:	245°C ± 5°C
	Solder Dwell Time:	4-6 seconds

Product Dimensions


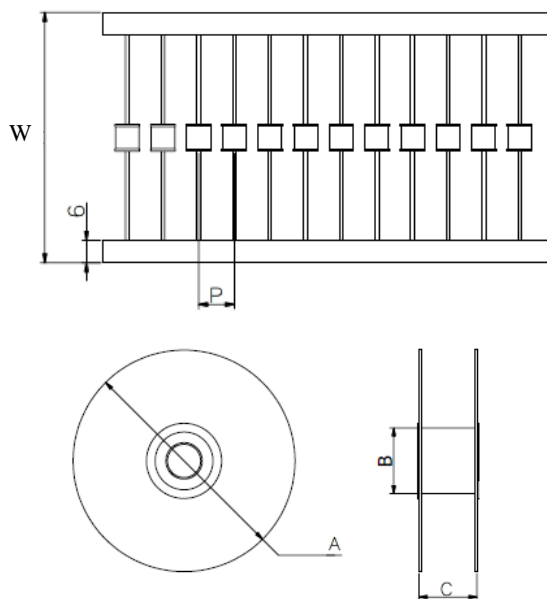
REF	mm	inch
A	62 ± 2	2.441 ± 0.079
B	6 ± 0.2	0.236 ± 0.008
C	$\Phi 5.5 \pm 0.2$	$\Phi 5.5 \pm 0.008$

Wave Soldering Profile

Wave Soldering Condition		Pb-Free assembly
Pre Heat	Temperature Min	100°C
	Temperature Max	150°C
	Time (min to max)	60 – 180 secs
Solder Pot Temperature		280°C Max
Solder Dwell Time		2-5 seconds



Package Reel Information



REF	mm	inch
W	65±3	2.559±0.118
P	10±1	0.394±0.039
A	Φ340±2	Φ13.386±0.079
B	Φ83±2	Φ3.268±0.079
C	73±3	2.874±0.118

OUTLINE	REEL (PCS)	PER CARTON (PCS)	CARTON SIZE(mm)		
			L	W	H
TAPING	1250	7500	480	350	360